

November 2013

FQD17N08L

N-Channel QFET® MOSFET

80 V, 12.9 A, 100 mΩ

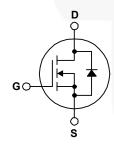
Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, • 100% Avalanche Tested DC motor control, and variable switching power applications.

Features

- 12.9 A, 80 V, $R_{DS(on)}$ = 100 m Ω (Max.) @ V_{GS} = 10 V, $I_D = 6.45 A$
- Low Gate Charge (Typ. 8.8 nC)
- Low Crss (Typ. 29 pF)





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter	FQD17N08LTM	Unit
V_{DSS}	Drain-Source Voltage	80	V
I _D	Drain Current - Continuous (T _C = 25°C)	12.9	Α
	- Continuous (T _C = 100°C)	8.2	Α
I _{DM}	Drain Current - Pulsed (Note 1)	51.6	Α
V_{GSS}	Gate-Source Voltage	± 20	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	100	mJ
I _{AR}	Avalanche Current (Note 1)	12.9	Α
E _{AR}	Repetitive Avalanche Energy (Note 1)	4.0	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	6.5	V/ns
P _D	Power Dissipation (T _A = 25°C) *	2.5	W
	Power Dissipation (T _C = 25°C)	40	W
	- Derate above 25°C	0.32	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C
T _L	Maximum lead temperature for soldering, 1/8" from case for 5 seconds	300	°C

Thermal Characteristics

Symbol	Parameter	FQD17N08LTM	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max. 3.13		
Ъ	Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max.	110	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (*1 in ² Pad of 2-oz Copper), Max.	50	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQD17N08LTM	FQD17N08L	DPAK	Tape and Reel	330 mm	16 mm	2500 units

Electrical Characteristics

T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	80			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.08		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 64 V, T _C = 125°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -20 V, V _{DS} = 0 V			-100	nA
	racteristics Cate Threshold Voltage	V = V Ι- = 250 μΔ	1.0		2.0	W
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0		2.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 6.45 \text{ A}$ $V_{GS} = 5 \text{ V}, I_D = 6.45 \text{ A}$		0.076 0.090	0.100 0.115	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 25 V, I _D = 6.45 A		11.7		S
Dynam	ic Characteristics				ı	
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,		400	520	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		120	155	pF
C _{rss}	Reverse Transfer Capacitance			29	37	pF
Switchi	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 40 V, I _D = 16.5 A,		7	25	ns
t _r	Turn-On Rise Time	$V_{DD} = 40 \text{ V, } I_D = 10.5 \text{ A,}$ $R_G = 25 \Omega$		290	590	ns
t _{d(off)}	Turn-Off Delay Time	- 1.6 - 20 22		20	50	ns
		4				

Drain	-Source	Diode	Characteristics	and Maximum	Ratings
Diam	Cource	Dioac	O I I di do lo I i o li o o	una maximan	i itatiiigs

Is	Maximum Continuous Drain-Source Diode Forward Current				12.9	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				51.6	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 12.9 A			1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 16.5 A,		55	/	ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs		85	//	nC

 $V_{GS} = 5 V$

 $V_{DS} = 64 \text{ V}, I_{D} = 16.5 \text{ A},$

Notes:

 t_{f}

 Q_g

 Q_{gs}

 Q_{gd}

- **Notes:** 1. Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 0.83 mH, I_{AS} = 12.9 A, V_{DD} = 25 V, R_{G} = 25 Ω , starting T_{J} = 25°C. 3. $I_{SD} \le$ 16.5 A, di/dt \le 300 A/ μ s, $V_{DD} \le$ BV $_{DSS}$, starting T_{J} = 25°C. 4. Essentially independent of operating temperature.

Turn-Off Fall Time

Total Gate Charge

Gate-Drain Charge

Gate-Source Charge

75

8.8

2.0

5.4

(Note 4)

160

11.5

ns

nC

nC

nC

Typical Characteristics

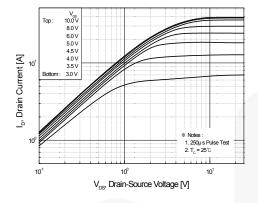


Figure 1. On-Region Characteristics

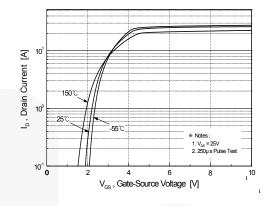


Figure 2. Transfer Characteristics

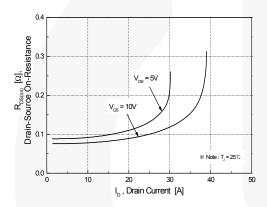


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

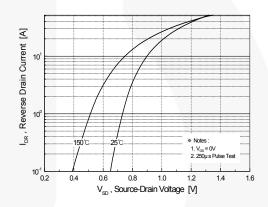


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

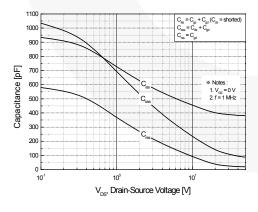


Figure 5. Capacitance Characteristics

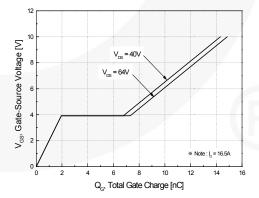


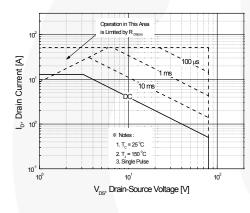
Figure 6. Gate Charge Characteristics

12 (Normalized) 1.1 (N

Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



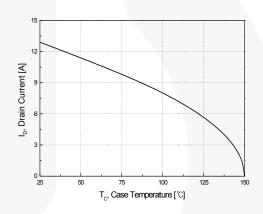


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

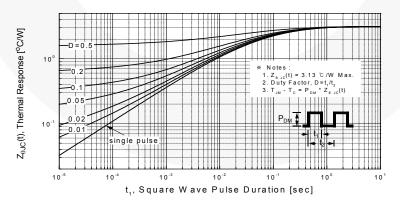


Figure 11. Transient Thermal Response Curve

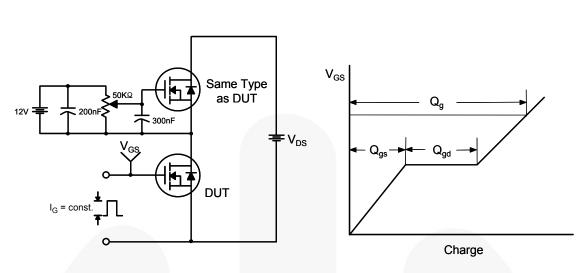


Figure 12. Gate Charge Test Circuit & Waveform

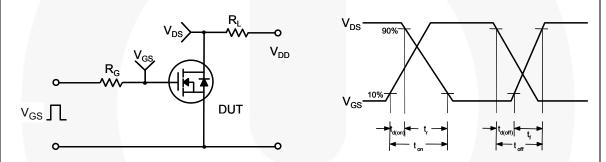


Figure 13. Resistive Switching Test Circuit & Waveforms

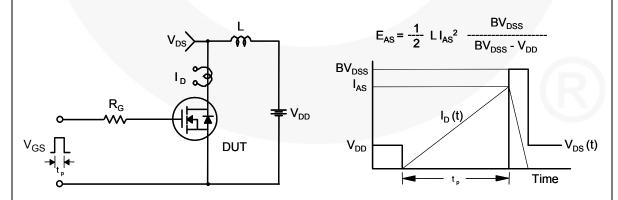
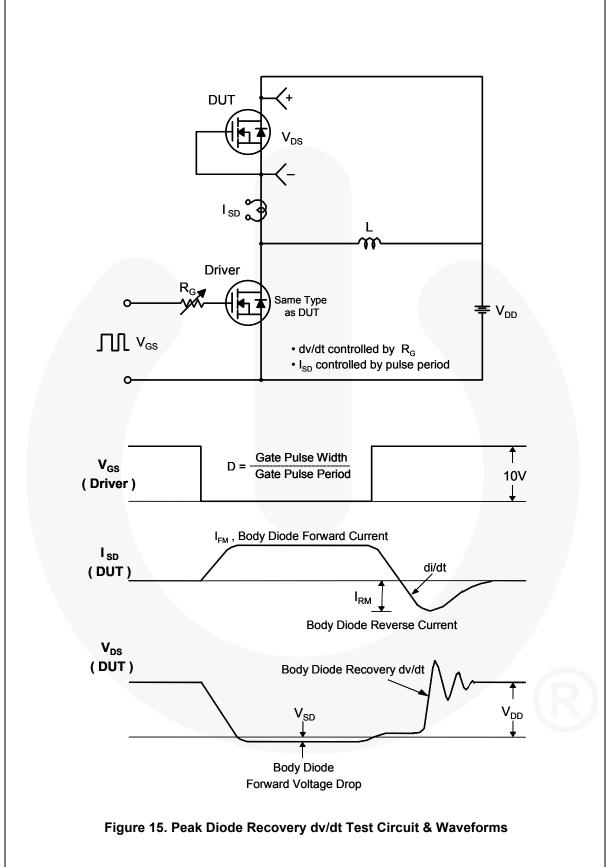
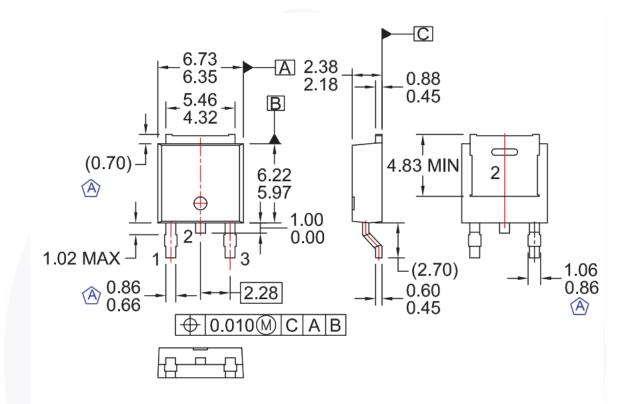


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

- (A) CONFORMS TO JEDEC TO-252 VARIATION AB EXCEPT WHERE NOTED
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DRAWING CONFORMS TO ASME Y14.5M-1994
- D) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- E) FORMERLY NAMED BD1733
- F) DRAWING FILE NAME: MKT-TO252D03REV1

Figure 16. TO-252 (D-PAK), Molded, 3-Lead, Jedec TO-252 VAR. AB, Surface Mount

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

http://www.fairchildsemi.com/package/packageDetails.html?id=PN_TO252-003





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™ AX-CAP® BitSiC™ Build it Now™ CorePLUS™ CorePOWER™ $CROSSVOLT^{\text{TM}}$

CTI ™ Current Transfer Logic™ DEUXPEED® Dual Cool™ EcoSPARK® EfficentMax™

Fairchild[®] Fairchild Semiconductor® FACT Quiet Series™ FACT® FAST® FastvCore™ FETBench™

ESBC™

F-PFS™ FRFET® Global Power ResourceSM GreenBridge™ Green FPS™

Green FPS™ e-Series™

G*max*™ GTO™ IntelliMAX™ ISOPLANAR™

Marking Small Speakers Sound Louder

and Better™ MegaBuck™ MICROCOUPLER™ MicroFET™ MicroPak™ MicroPak2™ MillerDrive™

MotionMax™ mWSaver® OptoHiT™ OPTOLOGIC® OPTOPLANAR® PowerTrench® PowerXS™

Programmable Active Droop™

QFET QS™ Quiet Series™ RapidConfigure™

Saving our world, 1mW/W/kW at a time™ SignalWise™

SmartMax™ SMART START™ Solutions for Your Success™

STEALTH™ SuperFET® SuperSOT™-3 SuperSOT™-6 SuperSOT™-8 SupreMOS® SvncFET™

SYSTEM®* TinyBoost[®] TinyBuck[®] TinyCalc™ TinyLogic[®] TINYOPTO™

Sync-Lock™

TinvPower™ TinyPWM™ TinyWire™ TranSiC™ TriFault Detect™ TRUECURRENT®* μSerDes™

UHC[®] Ultra FRFET™ UniFFT™ VCX™ VisualMax™ VoltagePlus™ XSTM

*Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FPS™

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY
FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE
EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used here in:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.Fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufactures of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handing and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS Definition of Terms

Datasheet Identification	Product Status	Definition		
Advance Information Formative / In Design		Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.		
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.		
No Identification Needed Full Production		Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.		
Obsolete Not In Production		Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.		

Rev. 166

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Fairchild Semiconductor: FQD17N08LTM